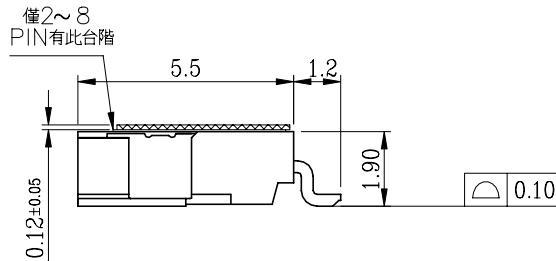
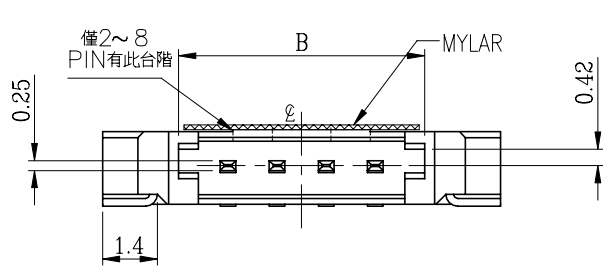


RECOMMENDED P.C. BOARD PATTERN DIM. (REF.)



- NOTES:
- MATERIAL:
 - HOUSING: HALOGEN FREE PLASTIC,UL94V-0.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - FINISH:
 - CONTACT:
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON CONTACT AREA
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" PURE TIN ON CONTACT AREA
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" MATT TIN ON CONTACT AREA
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL 15u" MIN GOLD ON CONTACT AREA
 - 100u"~150u" NICKEL UNDER PLATING OVER ALL 15u" MIN GOLD ON CONTACT AREA
 - 100u"~150u" NICKEL UNDER PLATING OVER ALL 30u" MIN GOLD ON CONTACT AREA
 - 100u"~150u" NICKEL UNDER PLATING OVER ALL 10u" MIN GOLD ON CONTACT AREA
 - SOLDER:
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" PURE TIN ON SOLDER AREA
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL 80u"~120u" MATT TIN ON SOLDER AREA
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - 100u"~150u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - 100u"~150u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - 3u" GOLD ON CONTACT GOLD FLASH ON SOLDER AREA
 - FITTING NAIL:
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER TAILS
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL 100u"~150u" PURE TIN ON SOLDER TAILS
 - 50u"~100u" NICKEL UNDER PLATING OVER ALL 100u"~150u" MATT TIN ON SOLDER TAILS
 - REFLOW SOLDER CAPABLE TO 260°C
 - PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50278-xxxx-xxx
 - PACKAGE PLS. REFER TO 88230-XX0X-TRP
 - PART NUMBER

P/N LEGEND	XXX	COLOR	PACKING
50278-XXX X X-XXX	001	BLACK	88230-XX0X-TRP
	002	NATURE	88230-XX0X-TRP
	003	BLACK	88230-XX0X-U-TRP

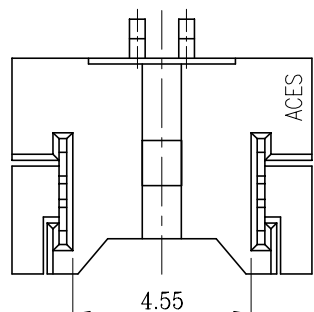
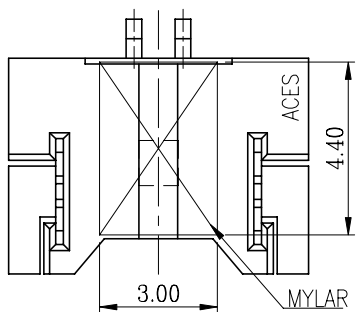
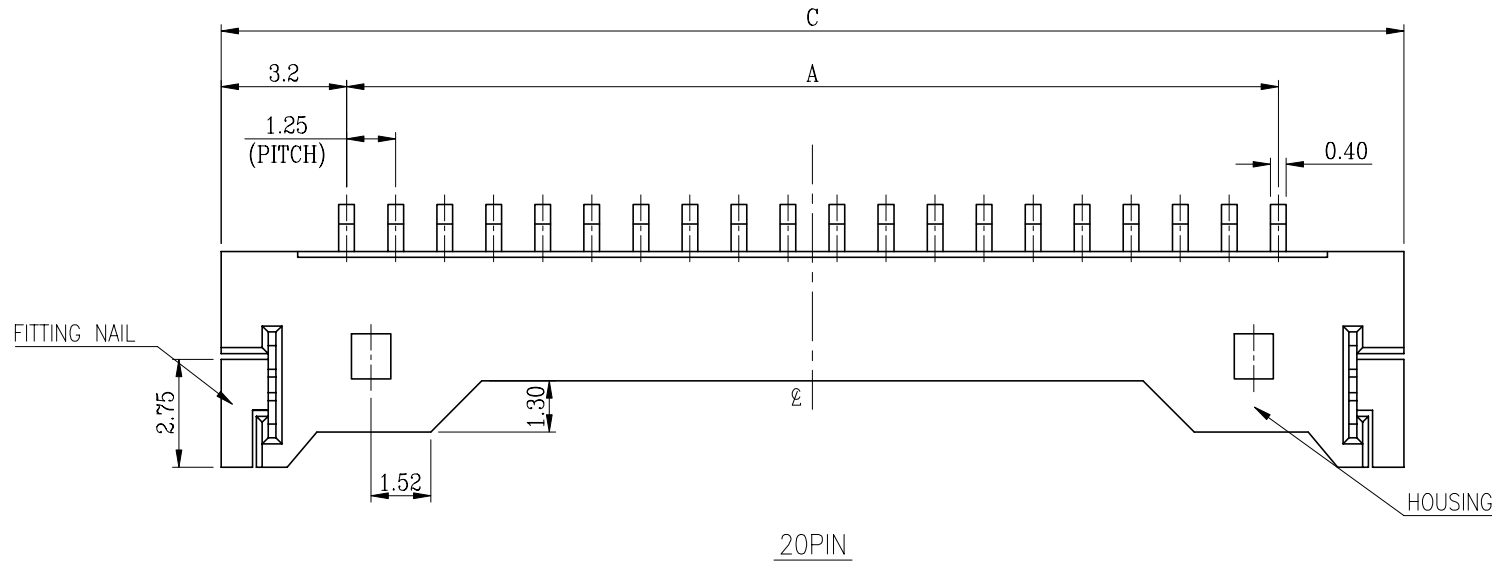
- PLATING
- L: PURE TIN
 - 1: GOLD FLASH
 - N: MATT TIN
 - C: CONTACT AREA:15u" GOLD PLATING SOLDER AREA: GOLD FLASH
 - W: CONTACT AREA:15u" GOLD PLATING SOLDER AREA: GOLD FLASH
 - D:30u" GOLD ON CONTACT(LEAD FREE) SOLDER AREA: GOLD FLASH
 - T:10u" GOLD ON CONTACT(LEAD FREE) SOLDER AREA: GOLD FLASH
 - A:3u" GOLD ON CONTACT(LEAD FREE) SOLDER AREA: GOLD FLASH
- PACKING
- O:TAPE&REEL(2~10PIN WITH MYLAR) (OTHER WITHOUT MYLAR)
 - 1:TUBE(2~10PIN WITH MYLAR) (OTHER WITHOUT MYLAR)
 - T:TAPE & REEL(WITHOUT MYLAR)
 - U:TUBE(WITHOUT MYLAR)

CKT.	DIM A	DIM B	DIM C	M/s(W)±0.10
2	1.25	3.77	7.65	3.00
3	2.50	5.02	8.90	3.00
4	3.75	6.27	10.15	6.00
5	5.00	7.52	11.40	6.00
6	6.25	8.77	12.65	6.00
7	7.50	10.02	13.90	10.00
8	8.75	11.27	15.15	10.00
9	10.00	12.52	16.40	10.00
10	11.25	13.77	17.65	12.00
11	12.50	15.02	18.90	X
12	13.75	16.27	20.15	X
14	16.25	18.77	22.65	X
15	17.50	20.02	23.90	X
16	18.75	21.27	25.15	X

QUALITY SYMBOLS		DRAWN BY		DATE	
MAJOR Ⓜ		TIANYINGHONG		21/05/18	
CRITICAL Ⓢ		CHECKED BY		DATE	
GENERAL TOLERANCES (UNLESS SPECIFIED)		XUZHUYONG		21/05/18	
X. ±0.5		APPROVED BY		DATE	
X. ±0.25		XUZHUYONG		21/05/18	
.XX ±0.15		UNITS		SIZE	
.XXX ±0.1		mm		A4	
ANGLES ±2°		SCALE		REV	
		1:1		Q	
		SHEET NO.		RFQ NO.	
		1 OF 2		N/A	
		DWG NO.			
				50278-XXXXX-XXX	



TITLE
1.25mm WIRE TO BOARD CONN.
LPF-2 SMT R/A TYPE



CKT.	DIM A	DIM B	DIM C	M/s(W)
20	23.75	26.27	30.15	X

QUALITY SYMBOLS		DRAWN BY	DATE	
MAJOR		TIANYINGHONG	21/05/18	
CRITICAL		CHECKED BY	DATE	
GENERAL TOLERANCES (UNLESS SPECIFIED)		XUZHUYONG	21/05/18	TITLE 1.25mm WIRE TO BOARD CONN. LPF-2 SMT R/A TYPE
X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°		APPROVED BY	DATE	
		XUZHUYONG	21/05/18	SIZE A4
		UNITS		RFQ NO. N/A
		SCALE	1:1	DWG NO. 50278-XXXXX-XXX
		SHEET NO.	2 OF 2	

单击下面可查看定价，库存，交付和生命周期等信息

[>>ACES\(宏致\)](#)